BEST AVAILABLE COPY

PATENT NUMBER

U.S. UTILITY Patent App	plication		
KW2 O.I.P.E.	. PATENT DATE	 	-
SCANNED GILL Q.A. OC			.,
SCANNED GIV Q.A. CL	<u> </u>		

CLASS	SUBCLASS		ART UNIT	F	EXAMINER	3.3
423			_ 144 9-00			
APPLICATION NO.	CONT/PRIOR CLAS	S SUBC	LASS A	RT LINIT	EVAMINED	

O9/490705 YES 438 SUBCLASS ART UNIT 1765

EXAMINER W. LCC

<u>⊈</u> Kazuyoshi Ueno S

Semiconductor device and a method for forming a via hole in a semiconductor device

×	40.00		6.74
	-) / X	٠.
劉 6		7 =	•
AND PARK ARE THE		_	_

PTO-2040

(Attached in pocket on right inside flap)

		ISSUING (CLASSII	FICATIO	DN			に出る
ORIGINA	L			CROSS R	EFERENC	E(S)		
CLASS	SUBCLASS	CLASS	SUB	CLASS (O	NE SUBCL	ASS PER I	BLOCK)	
to							7	F
INTERNATIONAL	CLASSIFICATION			-		4.		1.30
30	*			_==				
						L'		
						7		
	» · · · · ·				Continued o	n Issue Slip	Inside File Jac	cket

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED		
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
The term of this patent subsequent to (date)				NOTICE OF ALI	LOWANCE MAILED	
nas been disclaimed.	(Assistant	Examiner)	(Date)			
The term of this patent shall not extend beyond the expiration date				· •	0	
of U.S Patent. No.				ISSUE FEE		
- · · · · · · · · · · · · · · · · · · ·			Γ	Amount Due	Date Paid	
	(Primary E	xaminer)	(Date)			
The terminalmonths of his patent have been disclaimed.				ISSUE BAT	CH NUMBER	
no patent nave been discialmed.	(Legal Instrume	nts Examiner)	(Date)	*		
VARNING: he information disclosed herein may be res ossession outside the U.S. Patent & Tradem	tricted. Unauthorized o	fisclosure may be p	rohibited by the Ur	nited States Code Title 3	5, Sections 122, 181 and 368	